

**Amendments to the Claims are as follows:**

1. (Currently Amended) A thin-film capacitor element comprising:  
an insulative substrate having a via hole filled with a conductive material;  
a lower electrode;  
a dielectric layer; and  
an upper electrode; wherein the lower electrode, the dielectric layer, and the upper electrode are successively deposited in order on the insulative substrate, wherein  
either one of the lower electrode and the upper electrode connects to ~~an~~the end face of the conductive material; and  
the dielectric layer is shaped like a ring to surround the via hole.

2. (Currently Amended) A thin-film capacitor element according to Claim 1, wherein the dielectric layer is shaped like a ring with the via hole as ~~a~~the center.

3. (Original) A thin-film capacitor element according to Claim 1, wherein the insulative substrate is made of low-temperature-sintered ceramic.